



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-10-17
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Emilio Castelli	Representative Title	APG MD CHAMPION
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
TDA7721TR	ABYM*A232AB6	A	ZY1A	2013-10-17
Amount		UoM	Unit type	ST ECOPACK Grade
109.30		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	3	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
CHP	4.4x9.7x1.0	28	flat	
Comment				

Material Composition Declaration						Mfr Item Name	ABYM* A232AB6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other inorganic materials	8.893041753	mg	supplier	Silicon die	Silicon (Si)	7440-21-3		8.743	mg	983128	79991
Silicon Die			mg	supplier		Aluminium (Al)	7429-90-5		0.031041753	mg	3491	284
Silicon Die			mg	supplier		Titanium (Ti)	7440-32-6		0.013	mg	1462	119
Silicon Die			mg	supplier		Silicon Nitride (SiN)	68034-42-4		0.023	mg	2586	210
Silicon Die			mg	supplier		Silicon Oxide(SiO2)	7631-86-9		0.083	mg	9333	759
LEADFRAME	Copper and its alloy	51.01	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		48.388	mg	948598	442708
LEADFRAME			mg	supplier	ALLOY	Iron (Fe)	7439-89-6		1.192	mg	23368	10906
LEADFRAME			mg	supplier	ALLOY	Zinc (Zn)	7440-66-6		0.066	mg	1294	604
LEADFRAME			mg	supplier	ALLOY	Phosphorus (P)	7723-14-0		0.02	mg	392	183
LEADFRAME			mg	supplier	COATING	Silver(Ag)	7440-22-4		1.344	mg	26348	12296
DIE ATTACH	Other organic materials	1.793	mg	supplier	GLUE	Epoxy resin A	9003-36-5		0.125	mg	69716	1144
DIE ATTACH			mg	supplier	GLUE	Epoxy resin B	68475-94-5		0.072	mg	40156	659
DIE ATTACH			mg	supplier	GLUE	Silver(Ag)	7440-22-4		1.38	mg	769660	12626
DIE ATTACH			mg	supplier	GLUE	Lactone	96-48-0		0.072	mg	40156	659
DIE ATTACH			mg	supplier	GLUE	Polyoxypropylenediamine	9046-10-0		0.072	mg	40156	659
DIE ATTACH			mg	supplier	GLUE	2,6-Diglycidyl phenyl allyl ether oligomer	Trade secret		0.072	mg	40156	659
BONDING WIRE	Other inorganic materials	0.457	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		0.457	mg	1000000	4181
ENCAPSULATION	Other inorganic materials	44.423	mg	supplier	MOLDING COMPOUND	Epoxy Resin	Trade secret		3.998	mg	89998	36578
ENCAPSULATION			mg	supplier	MOLDING COMPOUND	Silica fused (SiO2)	60676-86-0		37.315	mg	839993	341400
ENCAPSULATION			mg	supplier	MOLDING COMPOUND	Phenol Resin	Trade secret		2.888	mg	65011	26423
ENCAPSULATION			mg	supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		0.222	mg	4997	2031
FINISHING	Other inorganic materials	2.724	mg	supplier	CONNECTION COATING	Tin (Sn)	7440-31-5		2.724	mg	1000000	24922